



*ITW*

**PATENT APPLICATION**

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re the Application of:

Confirmation No.: 7113

Yuichi INADA et al.

Art Unit: 1722

Application No.: 10/534,488

Examiner: Dimple N. Bodawala

Filed: May 11, 2005

Attorney Dkt. No.: 059559.00020

For: MOLDING DIE, MOLDING METHOD, DISC SUBSTRATE, AND MOLDING MACHINE

**RESPONSE UNDER 37 CFR § 1.111**

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

December 13, 2007

Sir:

In response to the Office Action dated September 19, 2007, please amend the above-identified application as set forth below.

**Amendments to the claims are submitted beginning on page 2.**

**Remarks are submitted beginning on page 7.**